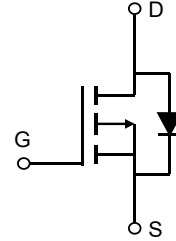


Description

Features

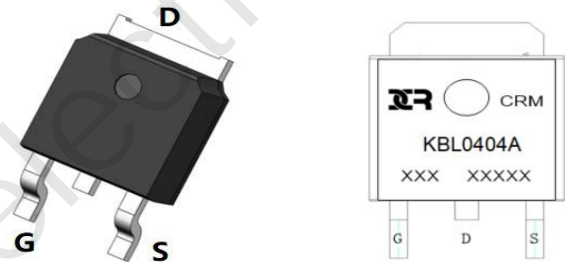
- -40V, -115A
 $R_{DS(ON)}$ Typ = 3.7mΩ @ $V_{GS} = -10V$
 $R_{DS(ON)}$ Typ = 4.9mΩ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKBL0404A	CRMKBL0404A	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-40	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-115
		$T_C = 100^\circ C$	-69
I_{DM}	Pulsed Drain Current ⁽¹⁾	-460	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	342	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	114
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.1	$^\circ C/W$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ C$

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} = 0V	-	-	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.1	-1.7	-2.4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = -10V, I _D = -20A	-	3.7	4.8	mΩ
		V _{GS} = -4.5V, I _D = -15A	-	4.9	6.4	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = -20V, f = 1MHz	-	7091	-	pF
C _{oss}	Output Capacitance		-	850	-	pF
C _{rss}	Reverse Transfer Capacitance		-	659	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to -10V V _{DS} = -20V, I _D = -20A	-	140	-	nC
Q _{gs}	Gate Source Charge		-	28	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	20	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = -20V I _D = -20A, R _{GEN} = 3Ω	-	15	-	ns
t _r	Turn-On Rise Time		-	40	-	ns
t _{d(off)}	Turn-Off DelayTime		-	320	-	ns
t _f	Turn-Off Fall Time		-	135	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-115	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-460	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -20A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I _F = -20A, di/dt = 100A/us	-	67	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	110	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=-20V, V_G=-10V, R_G=25ohm, L=0.5mH, I_{AS}=-37A
 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Test Circuit

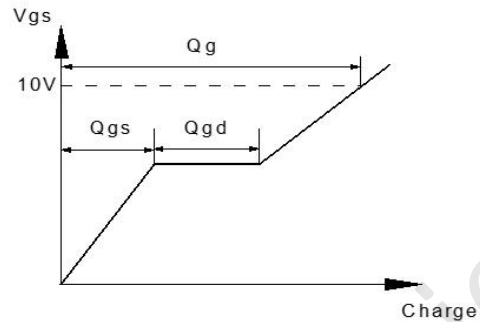
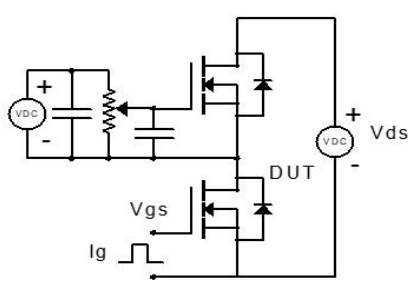


Figure 1: Gate Charge Test Circuit & Waveform

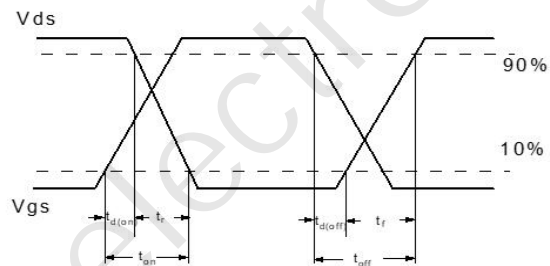
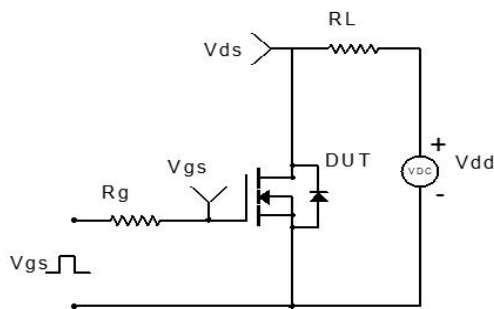


Figure 2: Resistive Switching Test Circuit & Waveform

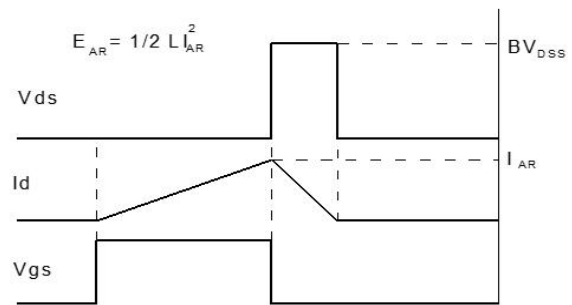
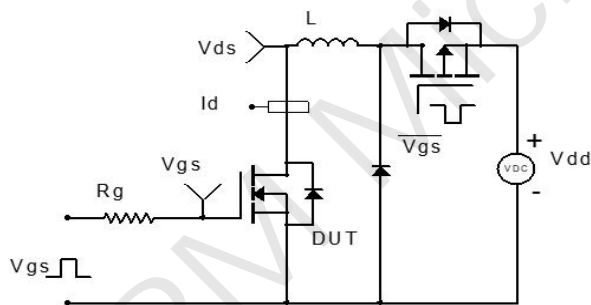


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

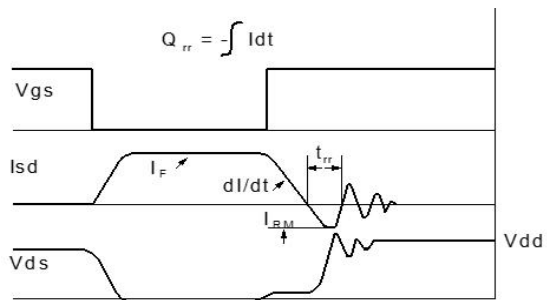
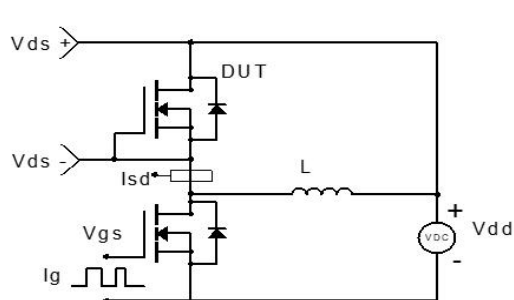
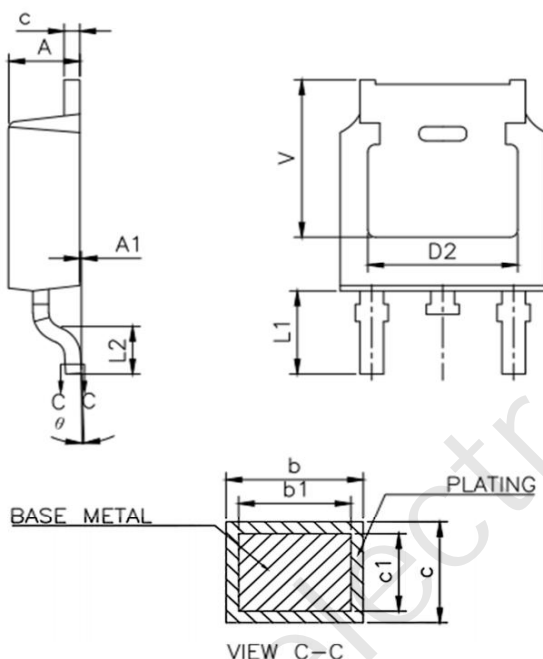
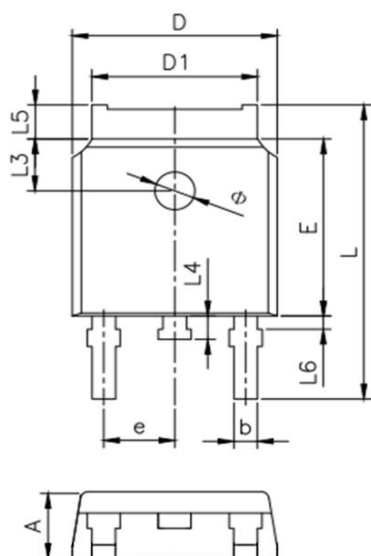


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	--	0.127
b	0.66	--	0.86
b1	0.65	0.76	0.81
D	6.50	6.60	6.70
D1	5.10	5.33	5.46
c	0.47	--	0.60
c1	0.46	0.51	0.56
D2	4.83 REF.		
E	6.00	6.10	6.20
e	2.186	2.286	2.386
L	9.80	10.10	10.40
L1	2.90 REF.		
L2	1.40	1.50	1.60
L3	1.80 REF.		
L4	0.60	0.80	1.00
L5	0.90	--	1.25
L6	0.15	--	0.75
Φ	1.10	--	1.30
θ	0°	--	8°
V	5.40 REF.		

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